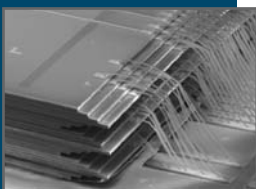
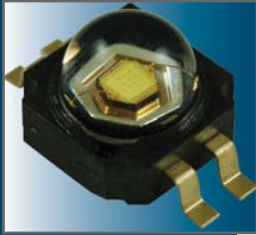


# Advanced Packaging Update: Market and Technology Trends

Vol. 3, 2008



Volume 3 of the Advanced Packaging Update for 2008 features an economic outlook for 2009 including an assembly and packaging equipment forecast. A special section is devoted to packaging for solid state drives. Examples of products are provided with photos. New through silicon via (TSV) developments are also described. Research results are provided for ASET (the Japanese government consortium), NEC, and Honda. Photos and manufacturing process flow details are provided for Toshiba's image sensor with TSV found in a Nokia mobile phone. Another special section is devoted to packaging for high-brightness light emitting diodes (LEDs).

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